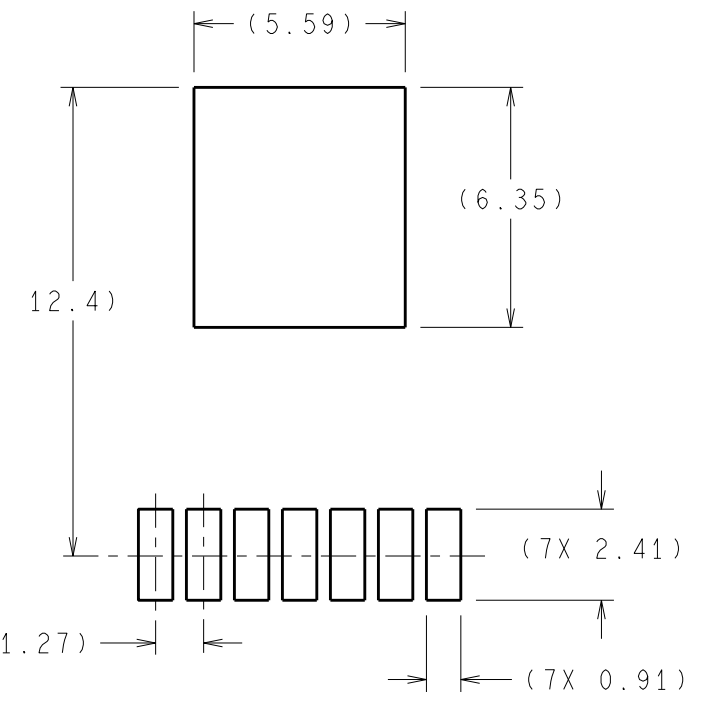
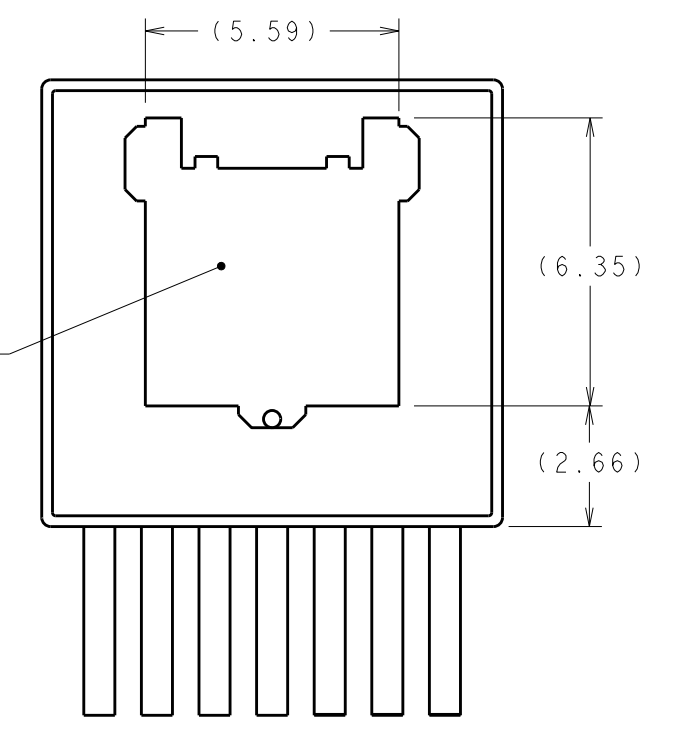
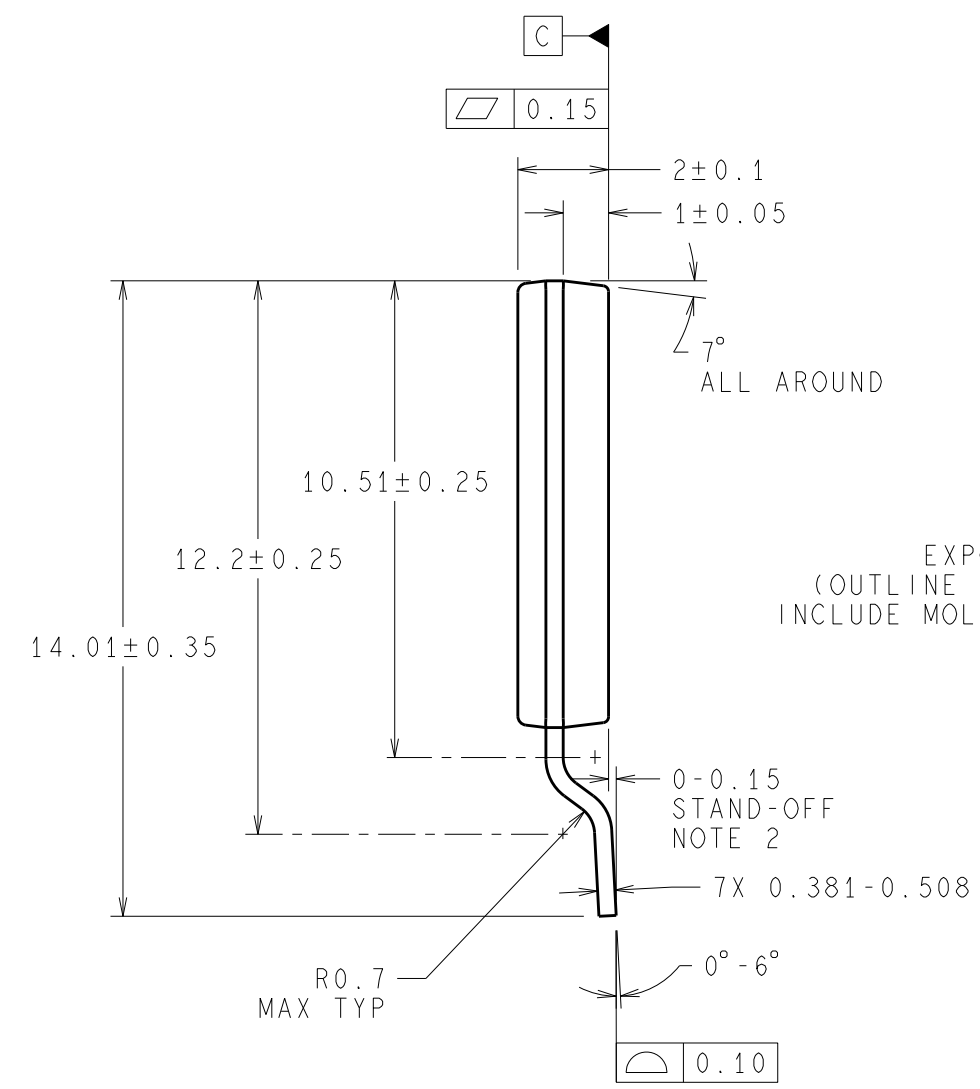
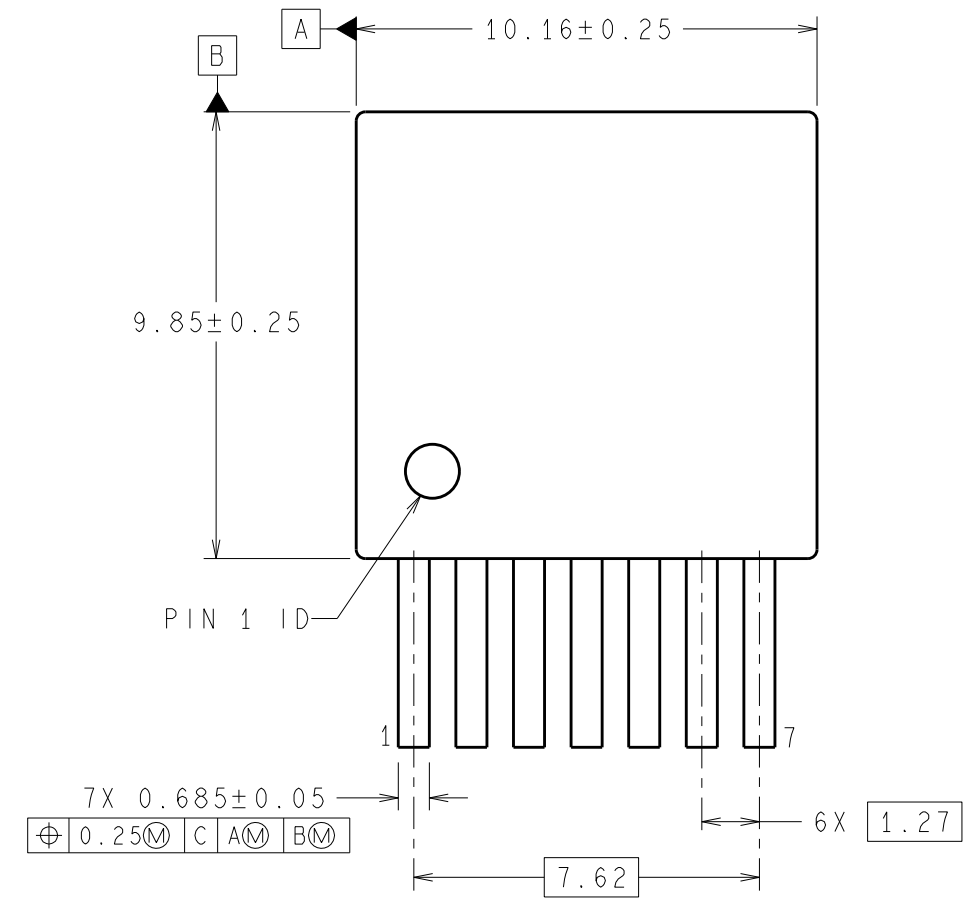


REVISIONS				
REV	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	2063	03/20/2006	AS/MS/AS
B	UPDATE EXPOSED DAP; UPDATE NOTE 3	2394	09/20/2007	EL/TL/EL
C	UPDATE NOTE 3; ADD "OUTLINE DOES NOT INCLUDE MOLD FLASH" UNDER EXPOSED DAP	2454	01/02/2008	EL/TL/EL
D	CORRECT THE NUMBER OF LD PITCH & LD COUNT IN THE LAND PATTERN	14138	08/10/2011	EL/TL/EL



RECOMMENDED LAND PATTERN

DIMENSIONS ARE IN MILLIMETERS
DIMENSIONS IN () FOR REFERENCE ONLY

NOTES: UNLESS OTHERWISE SPECIFIED

- FOR LEAD FINISH THICKNESS AND COMPOSITION, SEE "SOLDER INFORMATION" IN THE PACKAGING SECTION OF THE NATIONAL SEMICONDUCTOR WEB PAGE (www.national.com).
- UNDER ALL CONDITIONS, LEADS MUST NOT BE ABOVE DATUM C.
- REFERENCE JEDEC REGISTRATION TO-279B, VARIATION BC.

APPROVALS		DATE	 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN	ASINOR SULAIMAN	03/20/2006		
DFTG. CHK.	THANH LEQUANG	08/10/2011	THIN TO-263, MOLDED, 9.85x10.16x2.0mm, 7 LD, 1.27mm PITCH, SMT	
ENGR. CHK.	EUGENE LEE	08/10/2011		
PROJECTION	SCALE	SIZE	DRAWING NUMBER	REV
 MM	NTS	B	(SC)MKT-TJ7A	D
FORMERLY: N/A			SHEET 1 of 1	